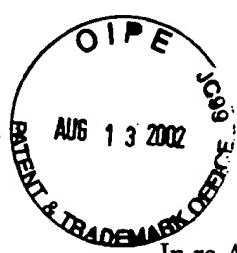


2814



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Todd O. Bolken

Serial No.: 09/516,080

Filed: March 1, 2000

For: EXPOSED DIE MOLDING  
APPARATUS

§ Group Art Unit: 2814  
§  
§  
§ Examiner: Louie, W.  
§  
§ Atty Docket: MICS:0043 FLE/MAN  
§ 99-0634

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

Sir:

RESPONSE AND AMENDMENT

In response to the Final Official Action mailed on June 5, 2002, Applicant respectfully requests reconsideration of the above-identified application in view of the remarks and amendments set forth below.

IN THE CLAIMS

Please cancel claim 15 without prejudice.

Please amend claims 1 and 16 as set forth below:

1. (twice amended) A system for molding a circuit package comprising:

a first support plate;

#9C Audit  
M. Brunson  
M. Brunson  
RECEIVED  
TECHNOLOGY CENTER 2800  
AUG 22 2002  
D 8/28/02